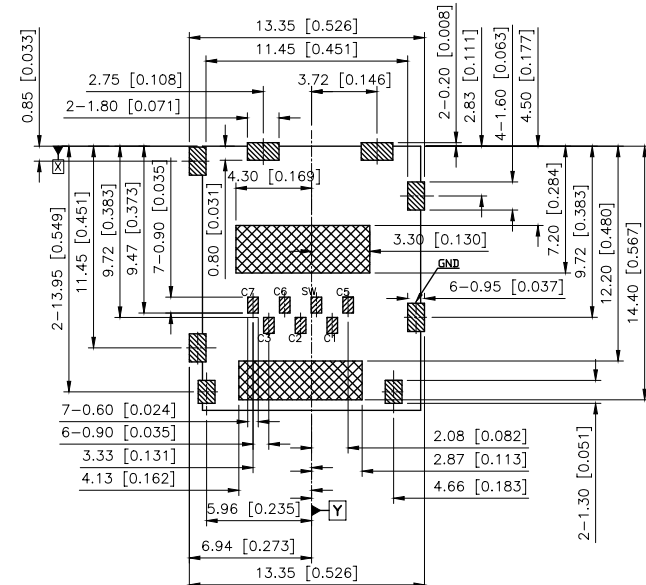
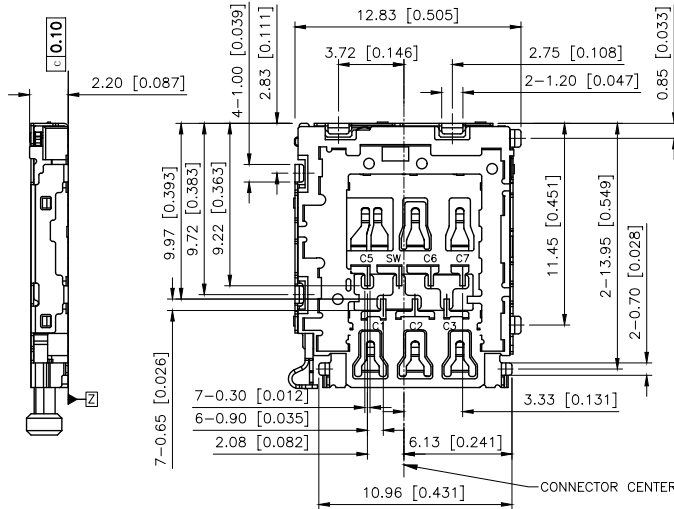
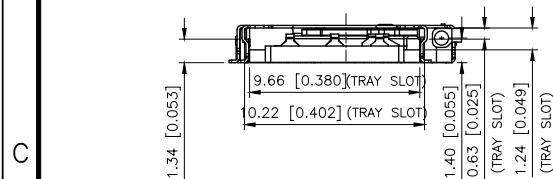
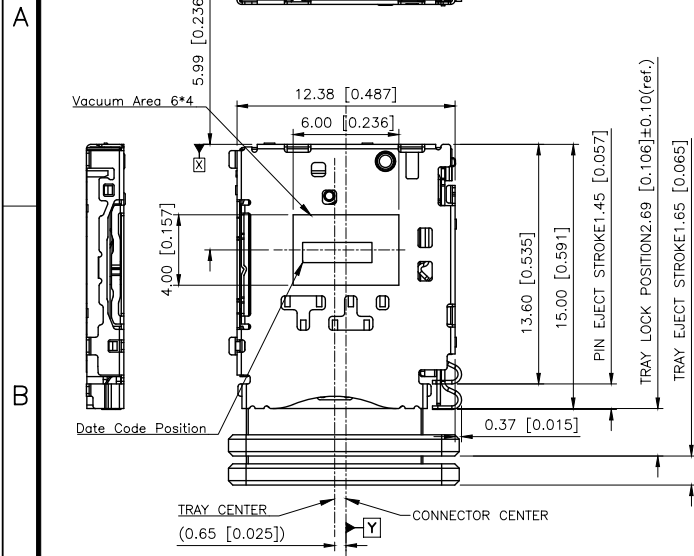


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.07	阿树



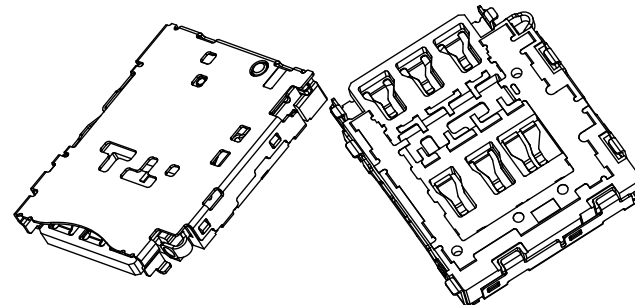
RECOMMEND P.C.B LAYOUT
(General tolerance ± 0.05)

▨ PAD AREA
▨ KEEP OUT AREA
▨ NO COPPER AREA
(NO Trace&Via&GND)
▨ GND PATTERN ONLY

COMPOSITION OF DETECTION	
CARD DETECT(SW)	
C5 SW	
CARD DETECTION/SWITCH	
CARD INSTALLATION:ON	
NON CARD:OFF	

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



- NOTE:
- 材料 Material:
 - 1-1 胶壳 Housing:High Temperature Thermoplastic(LCP S475)Color Black UL 94V-0
 - 1-2 触点 Contact:Phosphor Bronze(C5210R-H,T=0.10 $\pm$ 0.01mm)
 - 1-3 外壳 Cover:SUS301-HT=0.15 $\pm$ 0.03mm
 - 电镀 Plating:
 - 2-1 接触端子 Contact terminal:
 - 接触电阻 Contact area: Gold 1u" Min.
 - 焊接区 Solder area: Gold 0.8u" Min
 - 底镀 Underplating:Ni overall 50U" Min.
 - 2-2 外壳 Cover:
 - 底镀 Underplating: Ni overall 30U" Min.
 - 焊接区 Solder area: Gold 0.8u" Min.
 - 规格 Specification:
 - 3-1.额定电流 Current Rating :0.5A max.
 - 3-2.接触电阻 Contact Resistance:50 mOhms max
 - 3-3.绝缘电阻 Insulation Resistance:1000 MOhms min./500VDC
 - 3-4.耐电压 Dielectric Withstanding Voltage:500 V AC/1minute
 - 3-5.工作温度 Operating Temperature:-25℃ to+85℃
 - 3-6.插拔次数 Mating Cycles:5000 Insertions
 - Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
 - Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability,if Use A Metal Mask Less Than 0.15mm Thick.

AuGLAR	$\pm 5^{\circ}$
X.	± 0.40
X.x	± 0.30
X.xx	± 0.20
X.xxx	± 0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKNANO-1131-1
APPROVED		SIZE: A4	DWG NO.: X-XKNANO-1131-1
SCALE N/A			PAGE 1/1
			REVISION A1